

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Isao YOKOKAWA

Application No.: New U.S. Patent Application

Filed: June 28, 2006

Docket No.: 128503

For: METHOD FOR MEASURING AN AMOUNT OF STRAIN OF A BONDED  
STRAINED WAFER

**PRELIMINARY AMENDMENT**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

Please consider the following:

**Amendments to the Claims** as reflected in the listing of claims; and

**Remarks.**